DERWENT-ACC-NO:

1992-067414

DERWENT-WEEK:

199951

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TITLE:

Thin-film FET for memory - has source and

drain

electrodes buried in insulation film between

upper gate

electrode and film covering lower electrode

NoAbstract

Dwg 1/9

PATENT-ASSIGNEE: CASIO COMPUTER CO LTD[CASK]

PRIORITY-DATA: 1990JP-0092021 (April 9, 1990)

PATENT-FAMILY:

PUB-DATE LANGUAGE

PAGES MAIN-IPC

JP 03290970 A December 20, 1991 N/A

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JP 2969184 B2 November 2, 1999 N/A

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APPLICATION-DATA:

PUB-NO APPL-DESCRIPTOR APPL-NO

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H01L029/788 , H01L029/792

ABSTRACTED-PUB-NO: JP 2969184B

EQUIVALENT-ABSTRACTS:

Optical disk having a resin substrate has a trench on the periphery when the resin substrates are adhered to each other. A groove or pit for tracking is

formed on a side of a resin substrate. A lst ceramics layer, a

recording

layer, 2nd ceramics layer and a reflection layer are laminated in order. The

plates are adhered using epoxy gp. resin. A trench is formed at the periphery

and a UV curing type resin is filled into the trench. The resin is cured and

the periphery is cut.

ADVANTAGE - No change of mechanical characteristics at higher temp..

TITLE-TERMS: THIN FILM FET MEMORY SOURCE DRAIN ELECTRODE BURY INSULATE FILM

UPPER GATE ELECTRODE FILM COVER LOWER ELECTRODE

DERWENT-CLASS: Ull Ul2 Ul3 Ul4

EPI-CODES: U11-C18B5; U12-B03A; U12-D02A1; U12-Q; U13-C04B2; U14-A03B7; U14-H01A;

SECONDARY-ACC-NO:
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